



Product data sheet

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Features:

- Programmable output Voltage to 36 V
- Low dynamic output impedance
- Sink current capability of 1 to 100 mA
- Low output noise voltage
- Fast turn on response

SOT-23

1. Reference 2.Cathode 3. Anode

Absolute Maximum Ratings (T_a = 25 °C, unless otherwise noted.)

Parameter	Symbol	Value	Unit
Cathode Voltage	V _{KA}	36	V
Cathode Current Range (Continuous)	I _{KA}	- 100 to + 150	mA
Reference Input Current Range	I _{REF}	- 0.05 to + 10	mA
Power Dissipation	P _D	350	mW
Operating Temperature Range	T _{opr}	- 25 to + 85	°C
Junction Temperature	Tj	150	°C
Storage Temperature Range	T _{stg}	- 65 to + 150	°C

Recmmended Operating Conditions

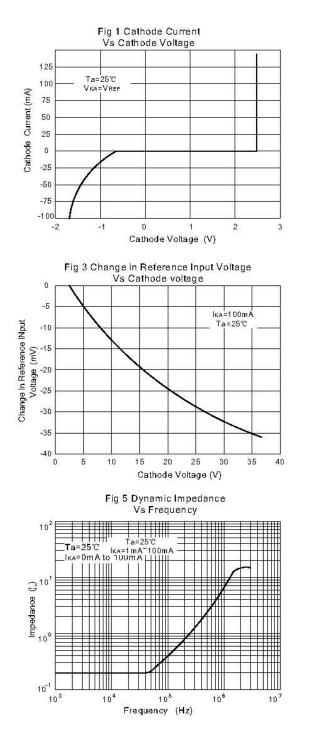
Parameter	Symbol	Min.	Max.	Unit
Cathode Voltage	V _{KA}	V_{REF}	36	V
Cathode Current	I _{KA}	1	100	mA

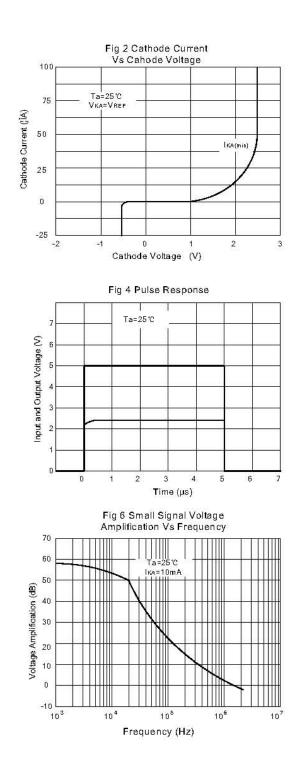
Characteristics at T_a = 25 °C

Parameter			Min.	Тур.	Max.	Unit
Reference Input Voltage						
at $V_{KA} = V_{REF}$, $I_{KA} = 10 \text{ mA}$	MMTL431	V_{REF}	2.44	2.495	2.55	V
	MMTL431A		2.48	2.495	2.51	
Deviation of Reference Input Voltage Over Temperatue			-	4.5	17	mV
at $V_{KA} = V_{REF}$, $I_{KA} = 10 \text{ mA}$, $-25 \text{ °C} \le T_a \le +$		/∆T				
Ratio of Change in Reference Input Voltage	to the Change					
in Cathode Voltage		$\Delta V_{\text{REF}} / \Delta$				mV/V
	= 10 V to V _{REF}	V _{KA}	-	-1.0	-2.7	111V/V
ΔV_{KA}	= 36 V to 10 V		-	-0.5	-2	
Reference Input Current		1		1.5	4	
at I _{KA} = 10 mA, R1 = 10 KΩ, R2 = ∞		I _{REF}	-	1.5	4	μA
Deviation of Reference Input Current Over I at I _{KA} = 10 mA, R1 = 10 KΩ, R2 = ∞, - 25°C		$\Delta I_{REF} / \Delta T$	-	0.4	1.2	μA
Minimum Cathode Current for Regulation		I _{KA(min)}	_	0.45	1	mA
at $V_{KA} = V_{REF}$		-104(11111)				
Off-Stage Cathode Current		I _{KA(OFF)}	-	0.05	1	μA
at V_{KA} = 36 V, V_{REF} = 0		·NA(OFF)			•	P 1
Dynamic Impedance		Z _{KA}	_	0.15	0.5	Ω
at $V_{KA} = V_{REF}$, $I_{KA} = 1$ to 100 mA, f ≤ 1 KHz		-nA		0.10	0.0	



TL431 HF Compiance

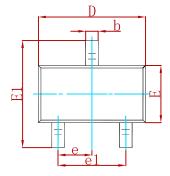


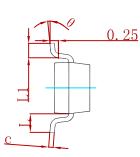


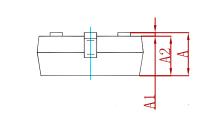


TL431 HF Semiconductor Compiance

PACKAGE MECHANICAL DATA

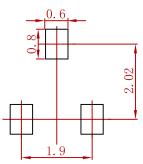






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950)TYP	0.037	7 TYP	
e1	1.800	2.000	0.071	0.079	
L	0.550) REF	0.022	2 REF	
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

Suggested Pad Layout



Note:

Controlling dimension:in millimeters.
General tolerance:± 0.05mm.
The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
TL431	SOT-23	3000





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